



Data and Signal Line Chokes

Common-mode chokes, ring core

Series/Type: B82793C0/S0

Date: May 2026

The following products presented in this data sheet are being withdrawn.

Ordering Code	Substitute Product	Date of Withdrawal	Deadline Last Orders	Last Shipments
B82793C0206N265		2024-03-15	2024-09-30	2024-12-31
B82793C0476N265		2024-03-15	2024-09-30	2024-12-31

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Rated voltage 42 V AC/80 V DC

Rated inductance 0.005 ... 47 mH

Rated current 100 ... 1200 mA

Construction

- Current-compensated double choke
- Ferrite core
- LCP case (UL 94 V-0), silicone potting
- Bifilar winding (B82793C0)
- Sector winding (B82793S0)



Features

- High rated currents, reduced components height
- Qualified to AEC-Q200 ($L \leq 4.7$ mH)
- Suitable for reflow soldering
- RoHS-compatible

Function

- B82793C0:
Suppression of asymmetrical interference coupled in on lines, whereas data signals up to some MHz can pass unaffectedly.
- B82793S0:
Suppression of asymmetrical and symmetrical interference (by L_{stray}) coupled in on lines. The high-frequency portions of the symmetrical data signal are decreased so far that EMC problems can be significantly reduced.

Applications

- Automotive applications, e.g. CAN bus
- Industrial applications
- Types with $L_R > 4.7$ mH only for telecom applications

Terminals

- Base material CuSn6
- Layer composition Ni, Sn
- Hot-dipped

Marking

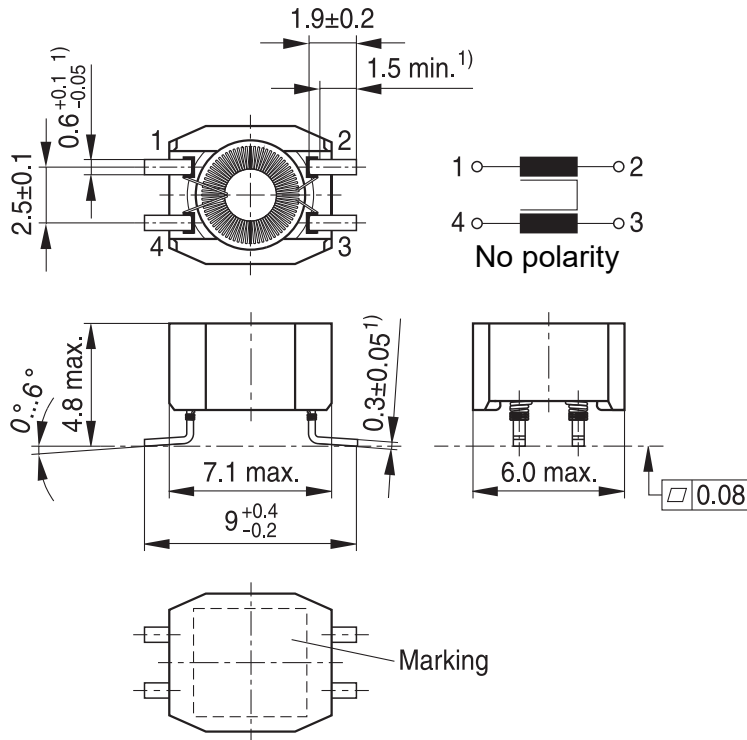
- Marking on component:
Manufacturer, process location (coded),
winding method (coded), ordering code (short form), date of manufacture (YWWD)
- Minimum data on reel: Manufacturer, ordering code,
L value and tolerance, quantity, date of packing

Delivery mode and packing unit

- 16-mm blister tape, wound on 330-mm $\varnothing$ reel
- Packing unit: 1500 pcs./reel

SMD

Dimensional drawing and pin configuration

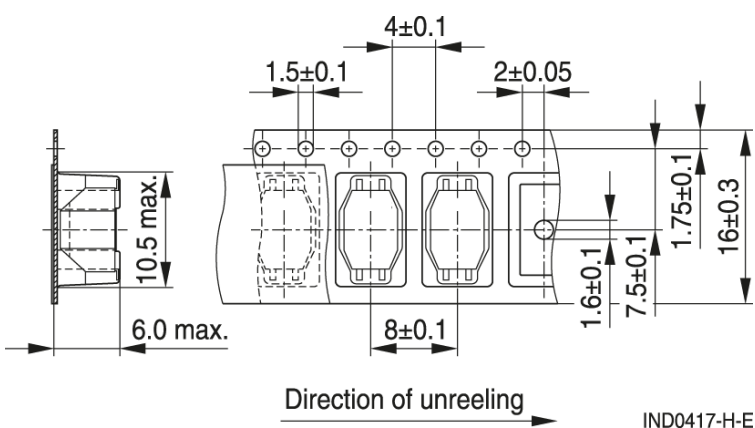


1) Soldering area

IND0010-9-E

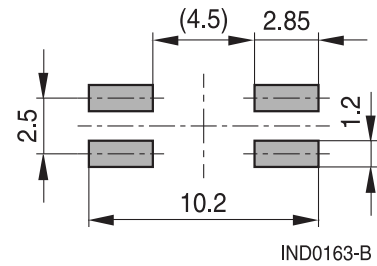
Taping and packing

Blister tape



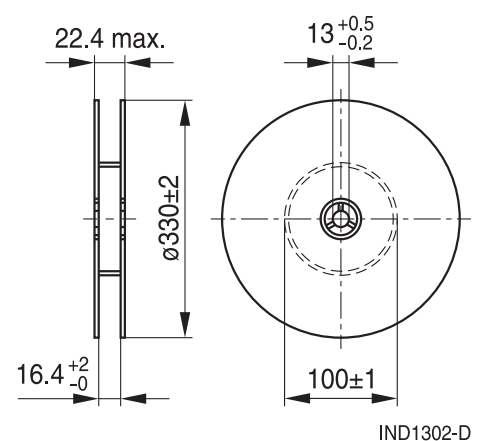
IND0417-H-E

Layout recommendation



Dimensions in mm

Reel



Dimensions in mm

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Technical data and measuring conditions

Rated voltage V_R	42 V AC (50/60 Hz) / 80 V DC
Rated temperature T_R	+60 °C
Rated current I_R	Referred to 50 Hz and rated temperature
Rated inductance L_R	Measured with Agilent 4284A, 0.1 mA, +20 °C Measuring frequency: $L_R \leq 1 \text{ mH} = 100 \text{ kHz}$ $L_R > 1 \text{ mH} = 10 \text{ kHz}$ Inductance is specified per winding.
Inductance tolerance	$\pm 30\%$ ($L_R \leq 0.47 \text{ mH}$), $-30/+50\%$ ($L_R \geq 1 \text{ mH}$) at +20 °C
Inductance decrease $\Delta L/L$	< 10% at DC magnetic bias with I_R , +20 °C
Stray inductance $L_{\text{stray, typ}}$	Measured with Agilent 4284A, 5 mA, +20 °C, typical values Measuring frequency: $L_R \leq 11 \mu\text{H} = 1 \text{ MHz}$ $L_R > 11 \mu\text{H} = 100 \text{ kHz}$
DC resistance R_{typ}	Measured at +20 °C, typical values, specified per winding
Solderability	SnPb: $+(215 \pm 3) \text{ °C}$, $(3 \pm 0.3) \text{ s}$ Sn96.5Ag3.0Cu0.5: $+(245 \pm 5) \text{ °C}$, $(3 \pm 0.3) \text{ s}$ Wetting of soldering area $\geq 95\%$ (to IEC 60068-2-58)
Resistance to soldering heat	$+(260 \pm 5) \text{ °C}$, $(10 \pm 1) \text{ s}$ (to IEC 60068-2-58)
Climatic category	40/125/56 (to IEC 60068-1)
Storage conditions (packaged)	$-25 \text{ °C} \dots +40 \text{ °C}$, $\leq 75\% \text{ RH}$
Weight	Approx. 0.25 g

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Characteristics and ordering codes

L_R mH	$L_{\text{stray, typ}}$ nH	I_R mA	R_{typ} m Ω	V_{test} V DC, 2 s	Ordering code
0.005	40	1200	60	250	B82793C0502N201
0.011	50	800	80	250	B82793C0113N201
0.025	60	800	110	250	B82793C0253N201
0.025	1400	800	110	250	B82793S0253N201
0.051	70	800	140	250	B82793C0513N201
0.051	2300	800	140	250	B82793S0513N201
0.10	100	500	180	250	B82793C0104N201
0.47	100	700	170	750	B82793C0474N215
1.0	70	700	140	750	B82793C0105N265
2.2	120	500	400	750	B82793C0225N265
4.7	250	400	550	750	B82793C0475N265
For telecommunications					
20	300	100	1800	750	B82793C0206N265
47	1200	100	3700	750	B82793C0476N265

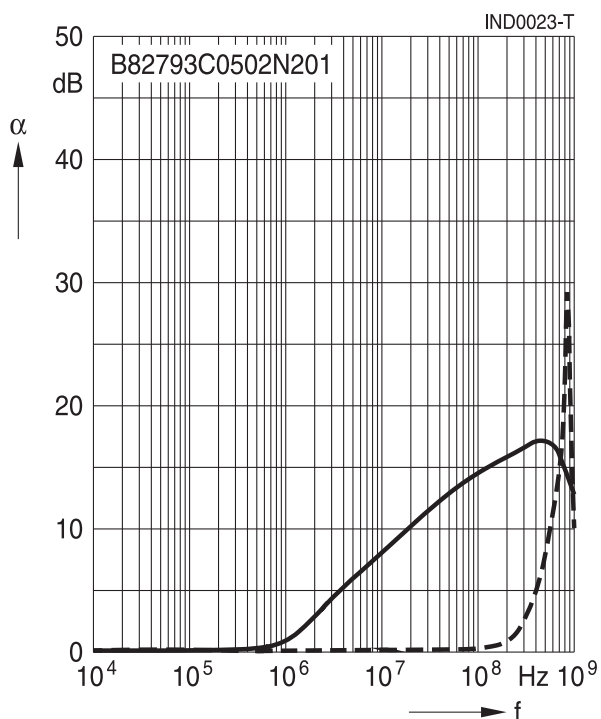
SMD

Insertion loss α (typical values at $|Z| = 50 \Omega$, $+20^\circ\text{C}$)

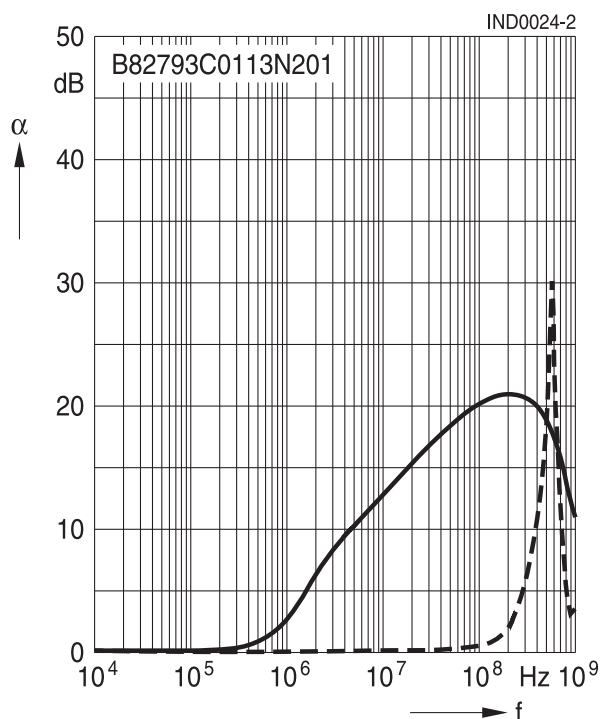
———— asymmetrical, all branches in parallel (common mode)

- - - - - symmetrical (differential mode)

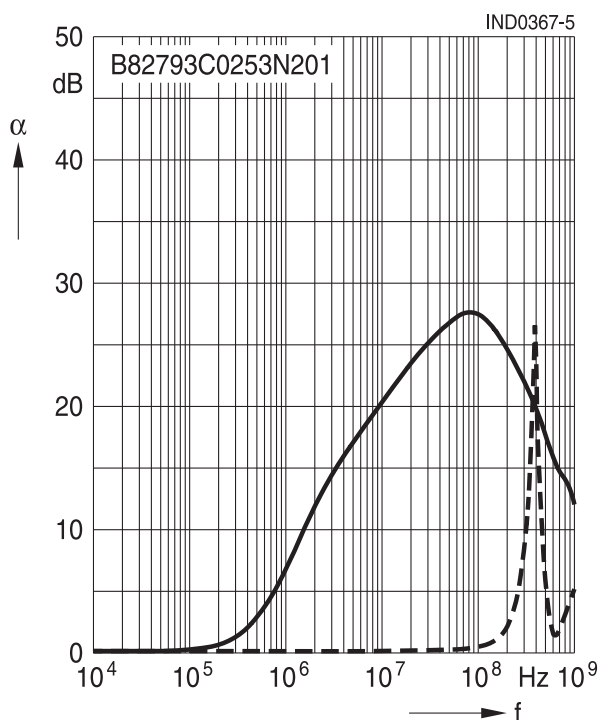
$L_R = 0.005 \text{ mH}$



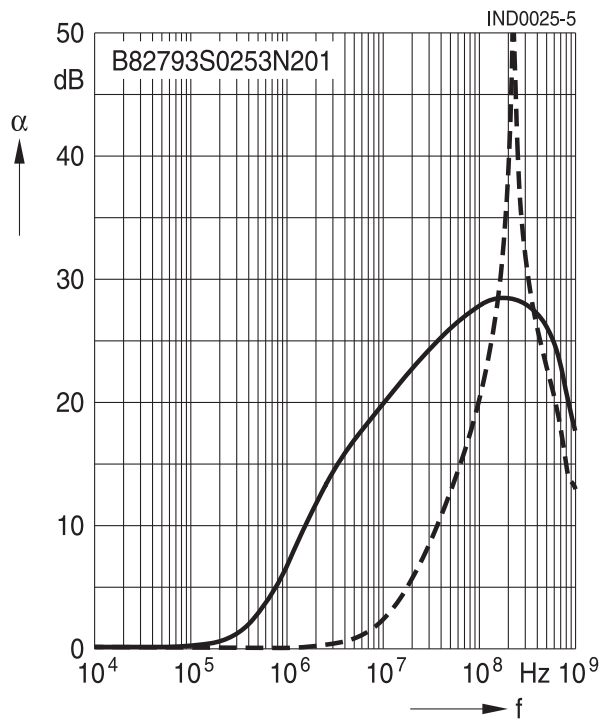
$L_R = 0.011 \text{ mH}$



$L_R = 0.025 \text{ mH}$ (low L_{stray})



$L_R = 0.025 \text{ mH}$ (high L_{stray})



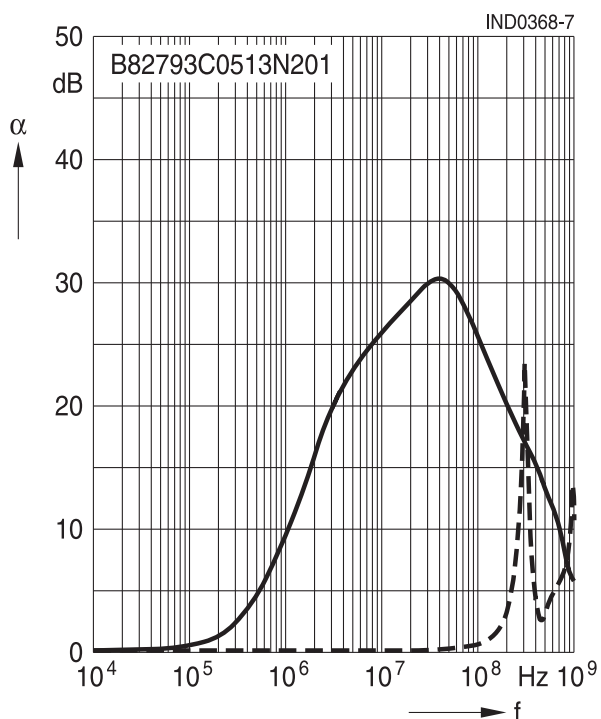
SMD

Insertion loss α (typical values at $|Z| = 50 \Omega$, $+20^\circ\text{C}$)

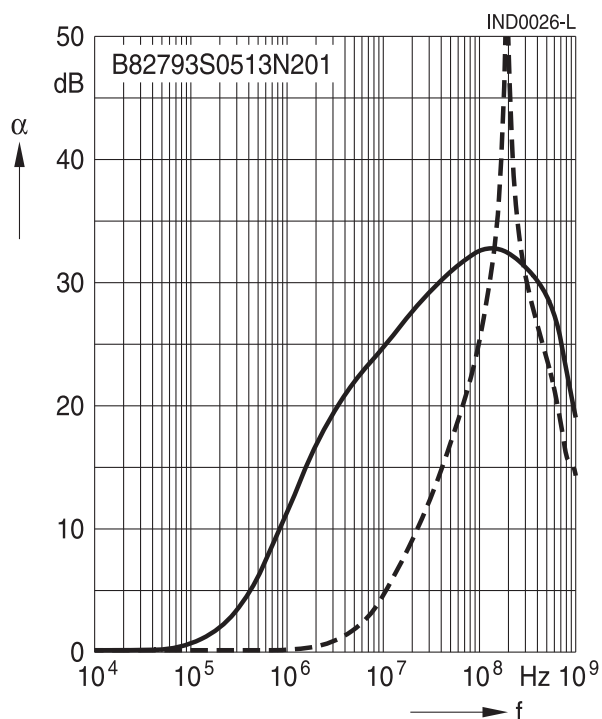
———— asymmetrical, all branches in parallel (common mode)

- - - - - symmetrical (differential mode)

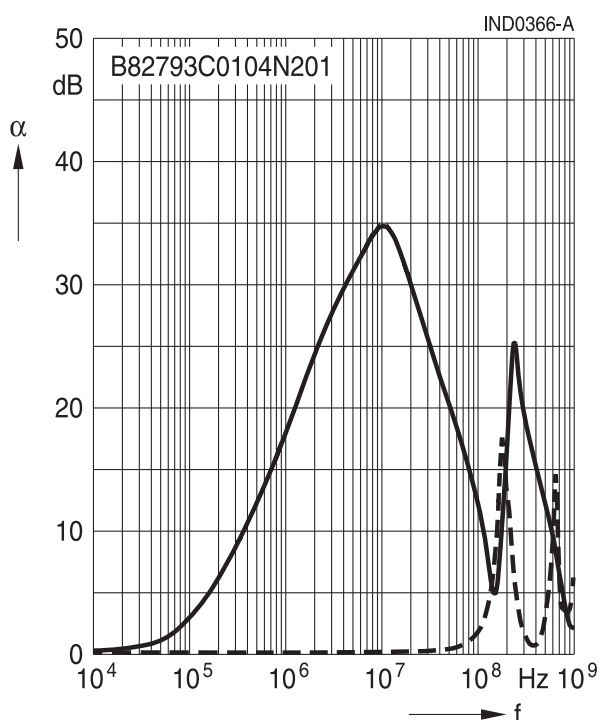
$L_R = 0.051 \text{ mH}$ (low L_{stray})



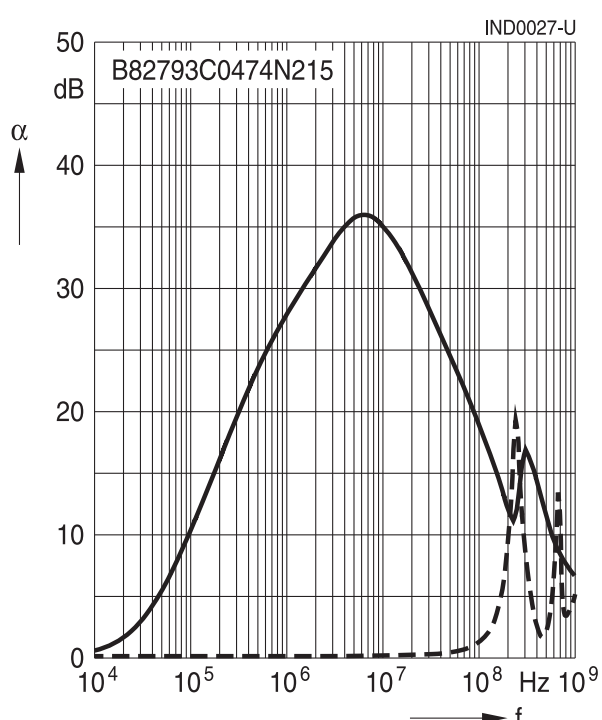
$L_R = 0.051 \text{ mH}$ (high L_{stray})



$L_R = 0.10 \text{ mH}$



$L_R = 0.47 \text{ mH}$



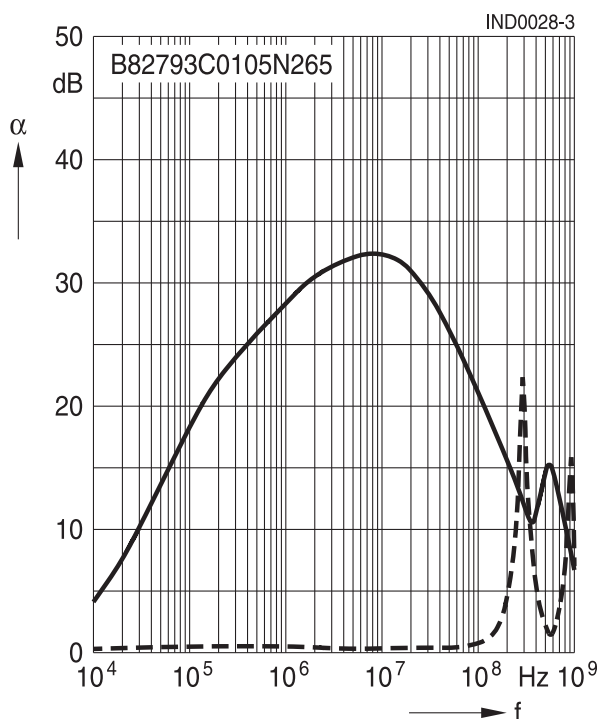
SMD

Insertion loss α (typical values at $|Z| = 50 \Omega$, $+20^\circ\text{C}$)

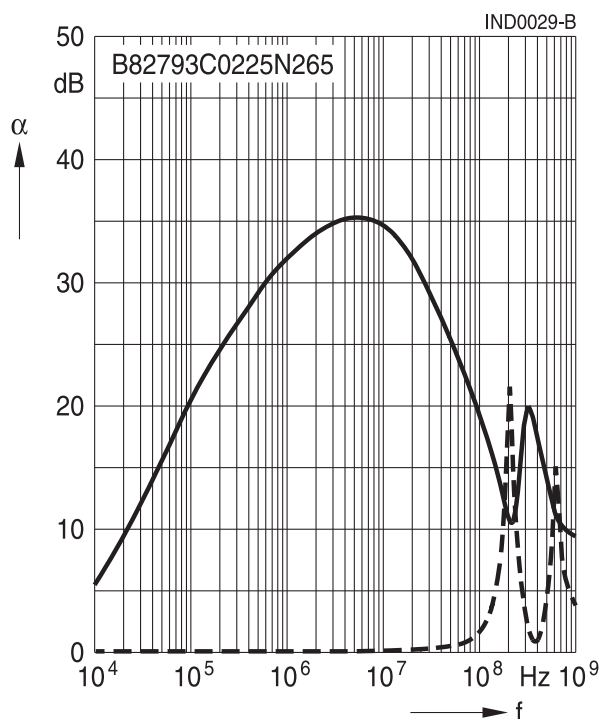
———— asymmetrical, all branches in parallel (common mode)

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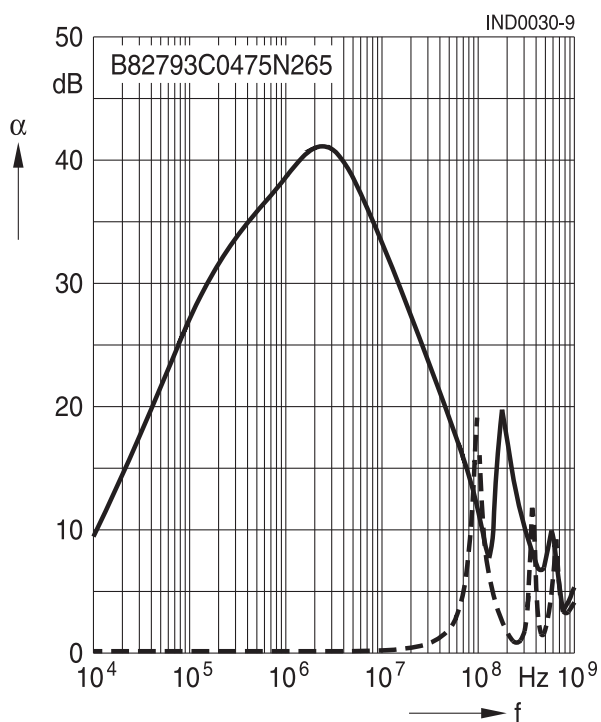
$L_R = 1.0 \text{ mH}$



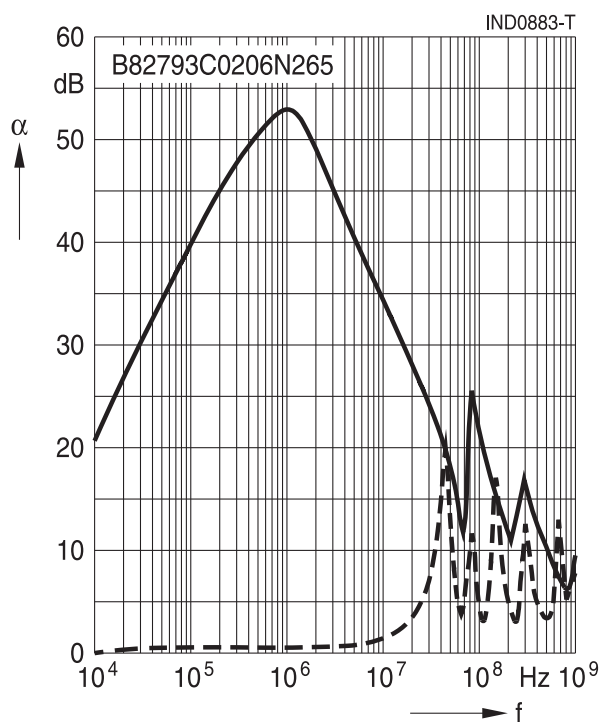
$L_R = 2.2 \text{ mH}$



$L_R = 4.7 \text{ mH}$



$L_R = 20 \text{ mH}$



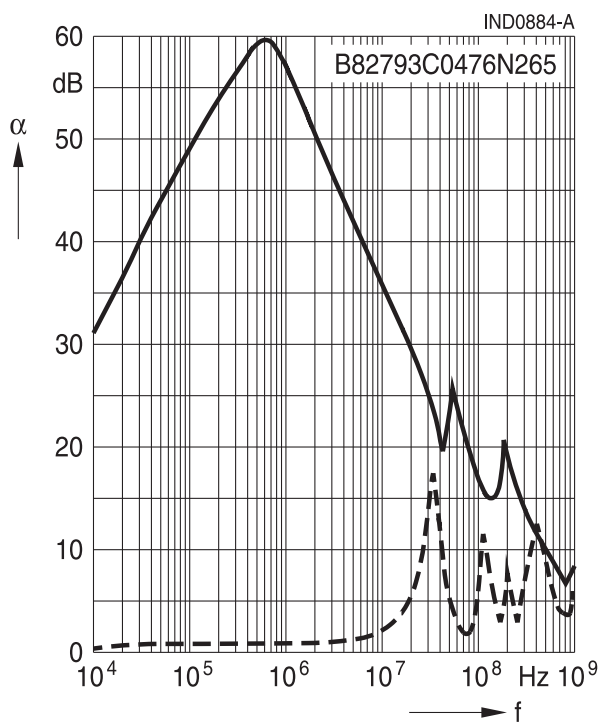
SMD

Insertion loss α (typical values at $|Z| = 50 \Omega$, $+20^\circ\text{C}$)

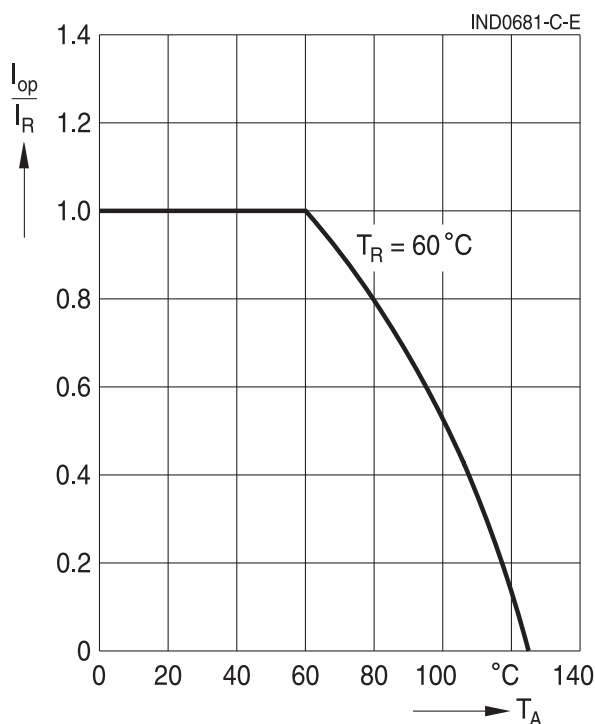
———— asymmetrical, all branches in parallel (common mode)

- - - - - symmetrical (differential mode)

$L_R = 47 \text{ mH}$



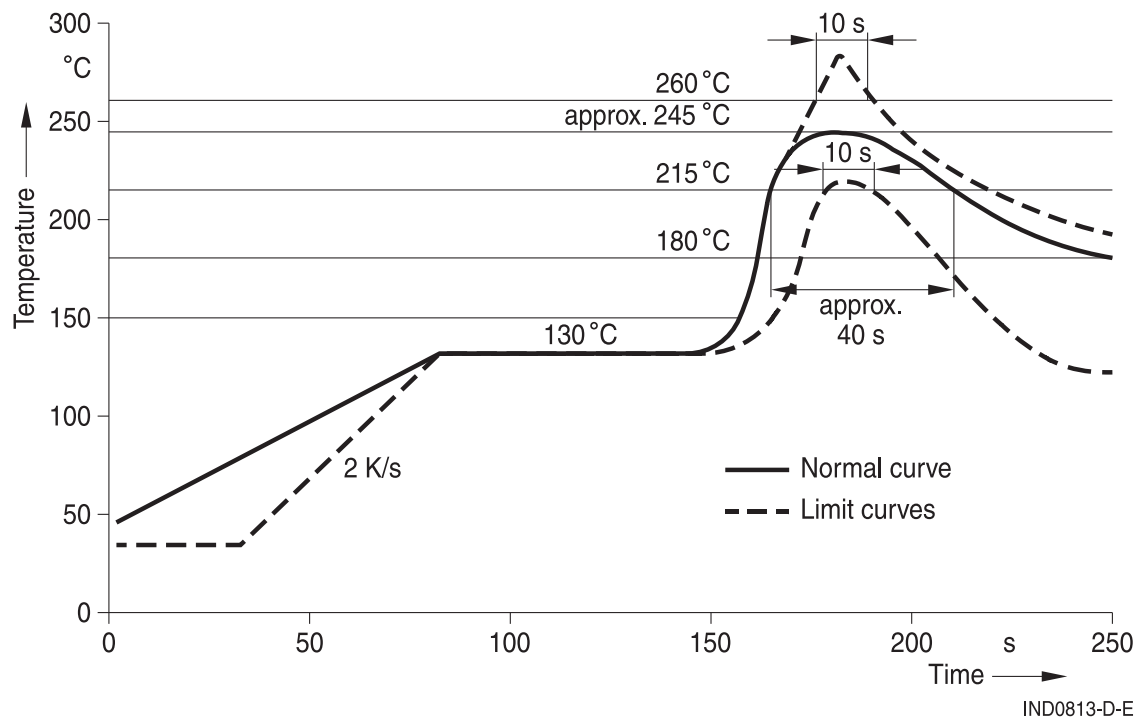
Current derating I_{op}/I_R
versus ambient temperature



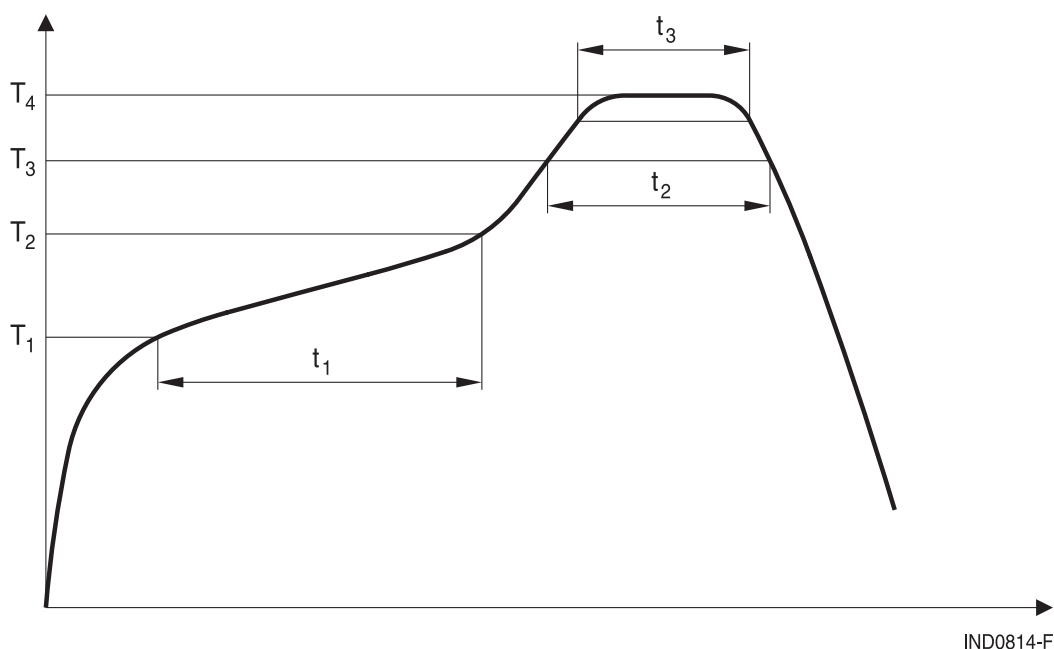
SMD

Recommended reflow soldering curve

Pb containing solder material (based on CECC 00802 edition 2)



Pb-free solder material (based on JEDEC J-STD 020D)



T_1 °C	T_2 °C	T_3 °C	T_4 °C	t_1 s	t_2 s	t_3 s
150	200	217	250	< 110	< 90	< 40 @ $T_4 - 5$ °C

Time from +25 °C to T_4 : max 300 s

Maximal numbers of reflow cycles: 3

Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition), online catalogs and in the data sheets.
 - Particular attention should be paid to the derating curves, if given. Derating applies in the case the ambient temperature in application exceeds the rated temperature of the component.
 - Ensure the operation temperature of the component in application not to exceed the maximum specified value or the upper climatic category temperature.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pins only. Temperatures specified in relation to reflow soldering can also refer to the pins or terminals for products with larger thermal mass, as in such cases, the temperature difference to the top of the component is too big (e.g., high proportion of core within the component).
- If the components are to be washed or varnished it is necessary to check whether the washing or varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. It is possible for washing or varnish agent residues to have a negative effect in the long-term on wire insulation.
 Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted, sealed, or varnished in customer applications:
 - Many potting, sealing, or varnishing materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting, sealing, or varnishing materials used attack or destroy the wire, wire insulation, plastics or glue.
 - The effect of the potting, sealing, or varnishing materials may change the high-frequency behavior of the components.
 - Many coating materials have a negative effect (chemically and mechanically) on the winding wires, insulation materials and connecting points. Customers are always obliged to determine whether and to what extent their coating materials influence the component. Customers are responsible and bear all risk for the use of the coating material. TDK Electronics does not assume any liability for failures of our components that are caused by the coating material.
- Magnetic core materials such as ferrites are sensitive to direct impact. This can cause the core material to flake or lead to breakage of the magnetic core material.
- Any type of tension or pressure on the product may result in damage and affect its functionality and reliability.
 - The products are only to be attached to fixings or mounting holes provided for this purpose in accordance with the data sheet.
 - If additional mechanical forces are applied to the component, e.g., application of gap pads, it is necessary to check whether they attack or destroy any part of the component.
 - It is not permitted for the product specified in the data sheet to assume a mechanical function in the final application.
- Inductance value can drop if external metallic or magnetic parts will be put close to the coil or into the air gap of the coil or core or magnetic material.

Cautions and warnings

- Due to product design and applied manufacturing process, appearance, symmetry, and shape of not dimensioned details could vary within same lot, as well discoloration of housing is possible. TDK does not expect detrimental effects on product function or reliability. In case of conflicts, TDK reference standard shall prevail.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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Important notes

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Release 2024-02